1	L Number	Hits	Search Text	DB	Time stamp
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272 156/345.51.ccls. EPO; JPO; DERWENT; IEM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT IEM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO; JPO; JPO; DERWENT; US-PGPUB; EPO; JPO	-	16		1	2003/06/10 16:05
- 272 156/345.51.ccls. DERWENT; IBM TDB USPAT; US-PGPUB; EFO; JPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EFO; JPO; JPO; JPO; JPO; JPO; JPO; JPO; JP			and (ica of icp of lapid adj thermal)	1	
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272 156/345.51.ccls. USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT USPAT; US-PGPUB; EPO; JPO; DERWENT; ISM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; US-PGPUB; EPO;				· ·	
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(chuck or tray or holder or frame) DERWENT;			<u>-</u>	•	
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	1109	(wafer or substrate) near2 (holder or carrier or tray or chuck or support) and (holder or carrier or tray or chuck or support) near6 (slot or groove or slit or notch) near6 (position or positioning or securing or positioned or aligning or aligned)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 17:14
	452		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 17:16
-	234		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/10 17:17
	42		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/11 14:04
_	1	(wafer or substrate) near2 (holder or carrier or tray or chuck or support) same (position or positioning) near3 kit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/11 14:05
	718	(position or positioning) near3 kit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/11 14:05
	16	(position or positioning) near3 kit near6 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/11 14:10
_	0	(position or positioning) adj3 kit near6 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/11 14:11
_	307	(position or positioning) adj3 kit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/11 14:12
	91	(position or positioning) adj kit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/11 14:12
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